

Turbo 2 ultrafast high voltage rectifier

Datasheet – production data

Features

- Ultrafast switching
- Low reverse recovery current
- Low thermal resistance
- Reduces switching losses
- ECOPACK®2 compliant component

Description

The STTH30W03C uses ST Turbo 2 300 V technology. It is especially suited to be used for DC/DC and DC/AC converters in secondary stage of MIG/MMA/TIG welding machine. Housed in ST's TO-247, this device offers high power integration for all welding machines and industrial applications.

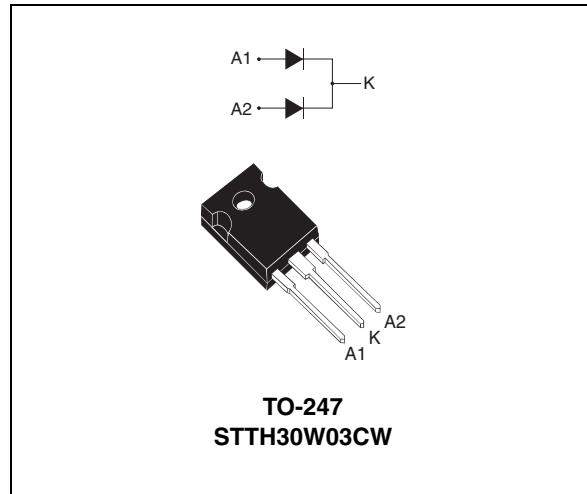


Table 1. Device summary

| Symbol | Value |
|----------------|----------|
| $I_{F(AV)}$ | 2 x 15 A |
| V_{RRM} | 300 V |
| t_{rr} (typ) | 20 ns |
| T_j | 175 °C |
| V_F (typ) | 0.90 V |

1 Characteristics

Table 2. Absolute ratings (limiting values, at 25 °C, unless otherwise specified)

| Symbol | Parameter | | | Value | Unit |
|--------------|---|--------------------------|------------|--------------|------|
| V_{RRM} | Repetitive peak reverse voltage | | | 300 | V |
| $I_{F(RMS)}$ | RMS forward current | | | 30 | A |
| $I_{F(AV)}$ | Average forward current, $\delta = 0.5$ | $T_c = 140$ °C | Per diode | 15 | A |
| | | $T_c = 130$ °C | Per device | 30 | |
| I_{FSM} | Surge non repetitive forward current | $t_p = 10$ ms sinusoidal | | 150 | A |
| T_{stg} | Storage temperature range | | | -65 to + 175 | °C |
| T_j | Maximum operating junction temperature | | | + 175 | °C |

Table 3. Thermal resistance

| Symbol | Parameter | | Value | Unit |
|---------------|------------------|-----------|-------|--------|
| $R_{th(j-c)}$ | Junction to case | Per diode | 1.7 | °C / W |
| | | Total | 1.0 | |
| $R_{th(c)}$ | Coupling | | 0.3 | |

When diodes 1 and 2 are used simultaneously:

$$T_{j(diode\ 1)} = P_{(diode\ 1)} \times R_{th(j-c)}(\text{Per diode}) + P_{(diode\ 2)} \times R_{th(c)}$$

Table 4. Static electrical characteristics

| Symbol | Parameter | Test conditions | | Min. | Typ | Max. | Unit |
|-------------|-------------------------|-----------------|-----------------|------|------|------|------|
| $I_R^{(1)}$ | Reverse leakage current | $T_j = 25$ °C | $V_R = V_{RRM}$ | | | 10 | μA |
| | | $T_j = 125$ °C | | | 10 | 100 | |
| $V_F^{(2)}$ | Forward voltage drop | $T_j = 25$ °C | $I_F = 15$ A | | | 1.40 | V |
| | | $T_j = 150$ °C | | | 0.90 | 1.10 | |
| | | $T_j = 25$ °C | $I_F = 30$ A | | | 1.6 | |
| | | $T_j = 150$ °C | | | 1.1 | 1.35 | |

1. Pulse test: $t_p = 5$ ms, $\delta < 2\%$
2. Pulse test: $t_p = 380$ μs, $\delta < 2\%$

To evaluate the conduction losses use the following equation:

$$P = 0.85 \times I_{F(AV)} + 0.0167 I_{F(RMS)}^2$$

Table 5. Dynamic electrical characteristics

| Symbol | Parameter | Test conditions | | Min. | Typ | Max. | Unit |
|----------|--------------------------|---------------------------|---|------|-----|------|------|
| I_{RM} | Reverse recovery current | $T_j = 125^\circ\text{C}$ | $I_F = 15 \text{ A}, V_R = 200 \text{ V}$ $dI_F/dt = -200 \text{ A}/\mu\text{s}$ | | 7 | 9 | A |
| Q_{RR} | Reverse recovery charge | | | | 160 | | nC |
| S_factor | Softness factor | | | | 0.3 | | |
| t_{rr} | Reverse recovery time | $T_j = 25^\circ\text{C}$ | $I_F = 1 \text{ A}, V_R = 30 \text{ V}$ $dI_F/dt = -100 \text{ A}/\mu\text{s}$ | | 20 | 25 | ns |
| t_{fr} | Forward recovery time | $T_j = 25^\circ\text{C}$ | $I_F = 15 \text{ A}, V_{FR} = 1.2 \text{ V}$ $dI_F/dt = 100 \text{ A}/\mu\text{s}$ | | | 230 | ns |
| V_{FP} | Forward recovery voltage | $T_j = 25^\circ\text{C}$ | | | 2.0 | 3.0 | V |

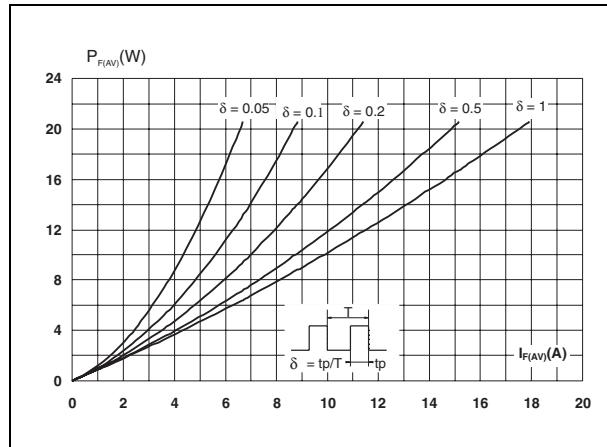
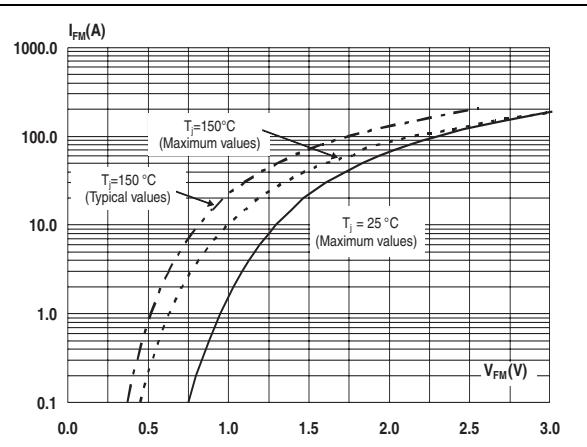
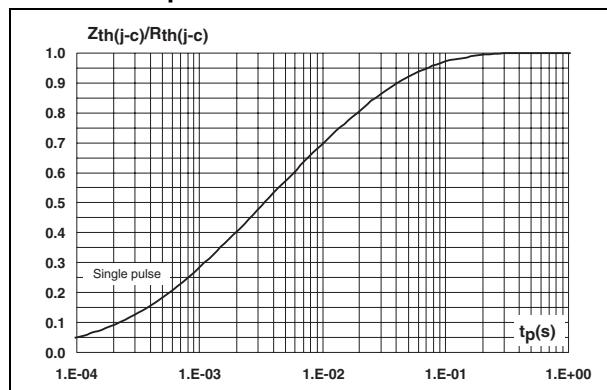
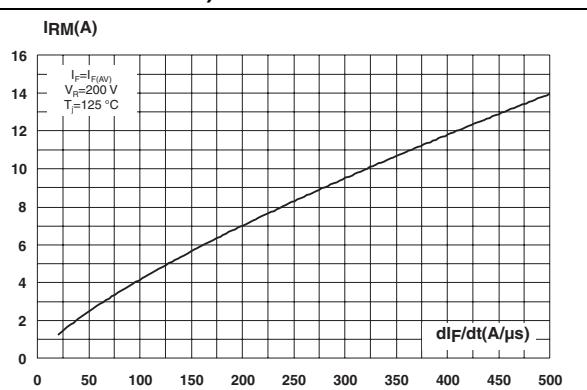
Figure 1. Average forward power dissipation versus average forward current (per diode)**Figure 2. Forward voltage drop versus forward current (per diode)****Figure 3. Relative variation of thermal impedance junction to case versus pulse duration****Figure 4. Peak reverse recovery current versus dI_F/dt (typical values, per diode)**

Figure 5. Reverse recovery time versus dI_F/dt (typical values, per diode)

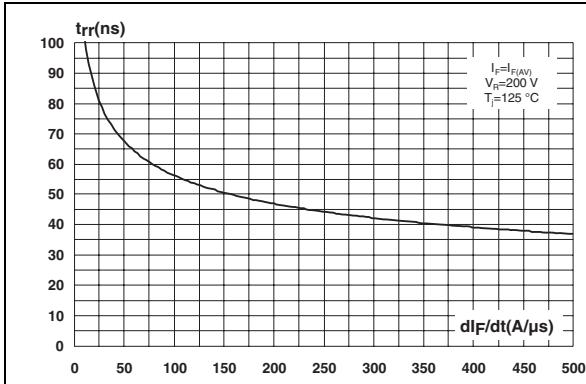


Figure 6. Reverse recovery charges versus dI_F/dt (typical values, per diode)

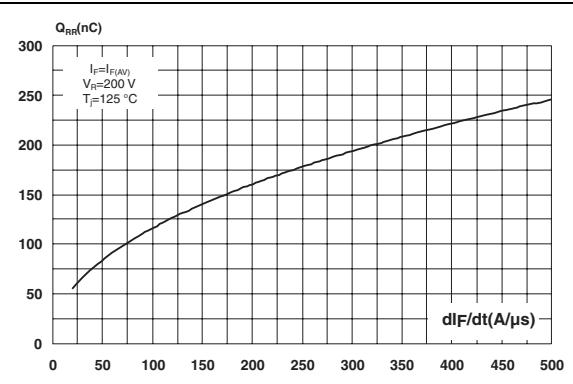


Figure 7. Relative variations of dynamic parameters versus junction temperature

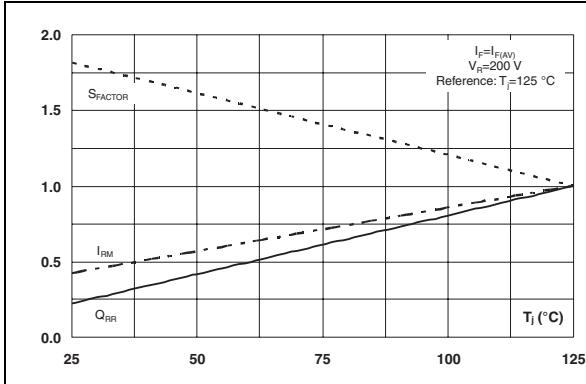


Figure 8. Reverse recovery softness factor versus dI_F/dt (typical values, per diode)

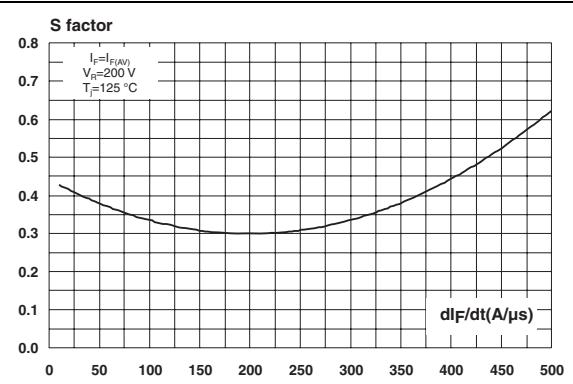


Figure 9. Forward recovery time versus dI_F/dt (typical values, per diode)

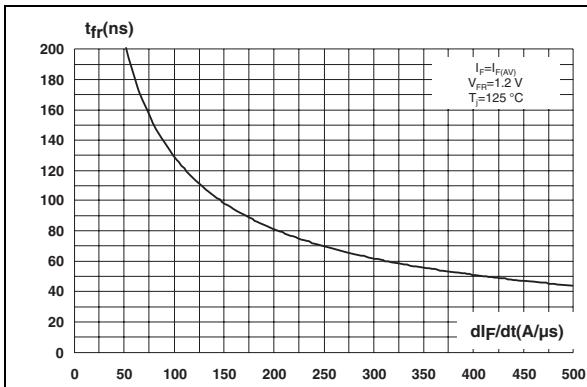


Figure 10. Transient peak forward voltage versus dI_F/dt (typical values, per diode)

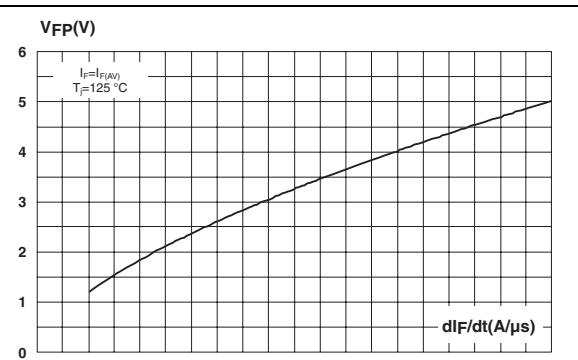
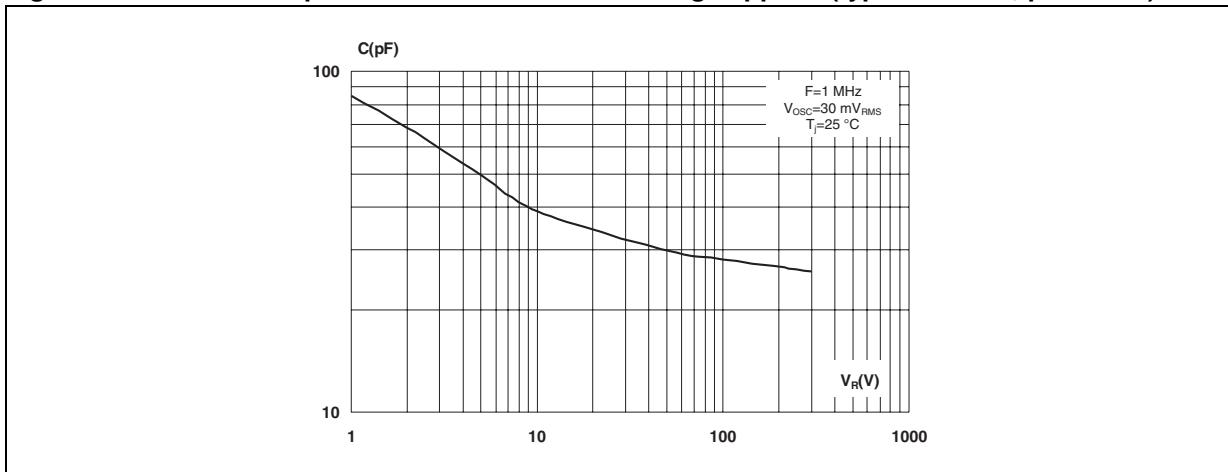


Figure 11. Junction capacitance versus reverse voltage applied (typical values, per diode)



2 Package information

- Epoxy meets UL94, V0
- Cooling method: by conduction (C)
- Recommended torque value: 0.55 N·m (1.0 N·m maximum)

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: www.st.com.
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Table 6. TO-247 dimensions

| Ref. | Dimensions | | | |
|------|-------------|-------|------------|-------|
| | Millimeters | | Inches | |
| | Min. | Max. | Min. | Max. |
| A | 4.85 | 5.15 | 0.191 | 0.203 |
| D | 2.20 | 2.60 | 0.086 | 0.102 |
| E | 0.40 | 0.80 | 0.015 | 0.031 |
| F | 1.00 | 1.40 | 0.039 | 0.055 |
| F1 | 3.00 typ. | | 0.118 typ. | |
| F2 | 2.00 typ. | | 0.078 typ. | |
| F3 | 2.00 | 2.40 | 0.078 | 0.094 |
| F4 | 3.00 | 3.40 | 0.118 | 0.133 |
| G | 10.90 typ. | | 0.429 typ. | |
| H | 15.45 | 15.75 | 0.608 | 0.620 |
| L | 19.85 | 20.15 | 0.781 | 0.793 |
| L1 | 3.70 | 4.30 | 0.145 | 0.169 |
| L2 | 18.50 typ. | | 0.728 typ. | |
| L3 | 14.20 | 14.80 | 0.559 | 0.582 |
| L4 | 34.60 typ. | | 1.362 typ. | |
| L5 | 5.50 typ. | | 0.216 typ. | |
| M | 2.00 | 3.00 | 0.078 | 0.118 |
| V | 5° typ. | | 5° typ. | |
| V2 | 60° typ. | | 60° typ. | |
| Dia. | 3.55 | 3.65 | 0.139 | 0.143 |

3 Ordering information

Table 7. Ordering information

| Ordering type | Marking | Package | Weight | Base qty | Delivery mode |
|---------------|-------------|---------|--------|----------|---------------|
| STTH30W03CW | STTH30W03CW | TO-247 | 4.46 g | 50 | Tube |

4 Revision history

Table 8. Document revision history

| Date | Revision | Changes |
|-------------|----------|--------------|
| 18-May-2012 | 1 | First issue. |

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